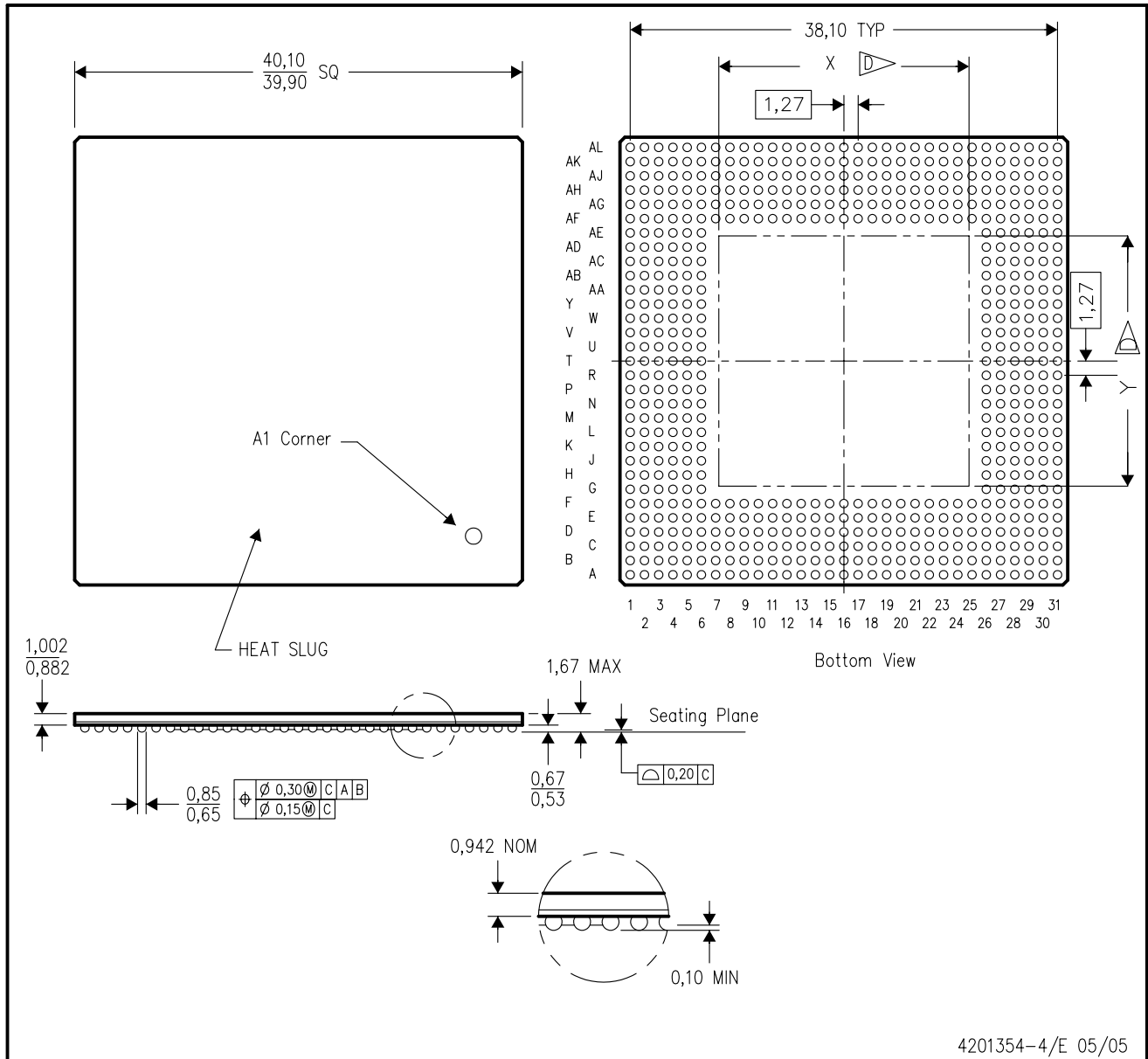


GPG (S-PBGA-N600)

PLASTIC BALL GRID ARRAY (CAVITY DOWN)



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Thermally enhanced plastic package with heat slug (HSL).
 - D. The encapsulation size (X,Y) will vary with cavity size. The distance from bond finger edge to encapsulation shall be min 0.50mm.

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